| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|----------|-------------------|
| 1 | 1 | ("6048754").PN. | USPAT | 2004/01/14 12:01 |
| 2 | 1 | (("6048754").PN.) and (semiconductor or device or chip | USPAT | 2004/01/14 12:09 |
| | | or substrate or electrode or pad or pads or plural or plurality | | |
| | , | or conductive or line or lones or region or first or second or | | |
| | | walls or mounting or connecting or supplying or encapsulating | | |
| | | or material or space or arrange or arranged or encapsulate) | | |
| 3 | 1 | ("5311060").PN. | USPAT | 2004/01/14 12:09 |
| 4 | 1 | (("5311060").PN.) and (semiconductor or device or chip | USPAT | 2004/01/14 12:09 |
| | | or substrate or electrode or pad or pads or plural or plurality | | |
| | | or conductive or line or lones or region or first or second or | | |
| | | walls or mounting or connecting or supplying or encapsulating | | |
| | | or material or space or arrange or arranged or encapsulate) | | |
| _ | 1 | ("5036024").PN. | USPAT | 2004/01/14 10:11 |
| - | 1 | ("5539250").PN. | USPAT . | 2004/01/14 10:11 |
| | 1 | ("4961105").PN. | USPAT | 2004/01/14 10:12 |
| - | i | ("5962917").PN. | USPAT | 2004/01/14 10:12 |
| _ | 1 | ("6048754").PN. | USPAT | 2004/01/14 10:12 |
| - | i i | ("5311060").PN. | USPAT | 2004/01/14 10:13 |
| _ | o | 09/616,378 | USPAT | 2004/01/14 10:14 |
| _ | ő | (chip adj region) and (pad adj region) and (conductive adj | USPAT | 2004/01/14 10:17 |
| | Ū | lines) and electrode and plurality and arranged | 45//11 | 200 1/01/11/10:17 |
| _ | o | (chip adj region) and (pad adj region) and (conductive adj | USPAT | 2004/01/14 10:18 |
| | | lines) and electrode and plurality | 451711 | 200 1/01/11/10:10 |
| _ | 5 | (conductive adj lines adj2 arranged) and chip and pad and | USPAT . | 2004/01/14 10:34 |
| | | electrode and plurality and region | 431711 | 200 170171110.31 |
| | 1 | (("5036024").PN.) and (semiconductor or device or chip | USPAT | 2004/01/14 10:45 |
| | • | or substrate or electrode or pad or pads or plural or plurality | d Si A i | 200 1/01/14 10:45 |
| | | or conductive or line or lones or region or first or second or | | |
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| | | or material or space or arrange or arranged or encapsulate) | | |
| _ | 1 | (("5539250").PN.) and (semiconductor or device or chip | USPAT | 2004/01/14 10:53 |
| | • | or substrate or electrode or pad or pads or plural or plurality | usi XI | 200 1/01/14 10.33 |
| | | or conductive or line or lones or region or first or second or | | |
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| _ | 1 | (("4961105").PN.) and (semiconductor or device or chip | USPAT | 2004/01/14 11:13 |
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| _ | 1 | (("5962917").PN.) and (semiconductor or device or chip | USPAT | 2004/01/14 12:01 |
| | 1 | or substrate or electrode or pad or pads or plural or plurality | UJI AT | 2007/01/17 12:01 |
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